IRPS 2012

IEEE International Reliability Physics Symposium

Sunday Tutorial Presentations

April 15, 2012

111: Probability and Statistics for the IC Reliability Engineer

112: Challenges in Accelerated Testing Due to Technology Scaling

113: Reliability Considerations in Key Ultra-Low Power Applications: Medical and Space

121: Front End of Line (FEOL) Reliability in CMOS Technologies

122: Reliability Physics of High-k/Metal Gate Stack

131: On-Chip ESD Protection Design for CMOS Integrated Circuits

132: System-Level ESD Reliability from an IC Perspective

133: Reliability Issues in Automotive Microelectronic Components and Systems

141: Failure Analysis: Applications and Challenges

142: Reliability of Advanced Packaging Technologies

143: Reliability of Cu/Low-k Interconnect Structures

144: System-level Design and Analysis for Thermo-Electro-Mechanical Reliability in Through-Silicon-Via Based 3D ICs